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FormFactor's Advanced Copper Pillar Probing Solutions Selected by Leading Semiconductor Foundries for Volume Production

Apollo(TM) MF100 Delivers MEMS Technology That Enables Copper Pillar Packaging Applications at Pitches of 100µm and Below

LIVERMORE, CA -- (Marketwired) -- 06/18/13 -- FormFactor Inc. (NASDAQ: FORM) announced today that it has shipped multiple units of Apollo™ MF100 probe cards to two leading semiconductor foundries. Following an extensive engineering evaluation, the foundries selected the Apollo™ MF100 to test advanced 28nm System-on-Chip products, utilizing copper pillar packaging technology, in volume production.

The transition to copper pillars is happening fast as semiconductor manufacturers deploy the new interconnect structure for its technology and cost advantages. By 2014, more than 50% of bumped wafers for Flip-Chip will be equipped with Cu pillars, and Cu pillar Flip-Chip is expected to grow at a Compound Annual Growth Rate (CAGR) of 35 percent between 2010 and 2018 in terms of wafer count, according to Yole Développement*.

The Apollo™ MF100 expands FormFactor's position in this high-growth sector. Popularly used for solder bump probing, the Apollo™ platform is now available with a vertical MEMS MF100 probe option creating a new high-precision/low-force technology solution for copper pillar applications. It is a highly customizable platform with application-specific probe options for targeted structures. Geared for multi-DUT (devices under test) testing in high-volume manufacturing environments, the product is optimized for robust performance and high throughput advantages that help lower overall test costs.

"Today's move marks two important developments," said Mike Slessor, Sr. Vice President and General Manager of the MicroProbe Product Group. "First, it applies our industry-leading MEMS technology to this high-growth segment of the market; and second, it extends the trusted and well-established Apollo™ vertical platform to our SoC customers' leading edge products at 28nm and beyond."

* "Flip-chip Market & Technology Trend - 2013 Business Update" - Yole Développement

About FormFactor

FormFactor Inc. (NASDAQ: FORM) is a leader in advanced wafer test solutions. The company's advanced wafer probe cards enable semiconductor manufacturers to lower their overall production costs, improve yields, and bring next-generation devices to market. FormFactor's acquisition of MicroProbe creates the leading wafer test solution provider for both memory and non-memory semiconductor manufacturers. FormFactor is headquartered in Livermore, California with operations in Europe, Asia and North America. For more information, visit the company's website at www.formfactor.com.

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Forward-looking Statements:

Statements in this press release that are not strictly historical in nature are forward-looking statements within the meaning of the federal securities laws, including statements regarding anticipated results, market conditions or trends, expectations and operating plans. These forward-looking statements are based on current information and expectations that are inherently subject to change and involve a number of risks and uncertainties. Actual events or results might differ materially from those in any forward-looking statement due to various factors, including, but not limited to: our ability to successfully integrate and realize the anticipated benefits of the Astria Semiconductor Holdings, Inc. acquisition, including MicroProbe Incorporated; risks of the company's ability to meet customers' test roadmaps; risks arising from structural changes in the computing industry; seasonal cyclicality of our business; risks of the company's ability to realize further operational efficiencies and achieve synergies through the MicroProbe integration; and changes in the market and macro-economic environments. Additional information concerning factors that could cause actual events or results to differ materially from those in any forward-looking statement is contained in the company's Form 10-K for the fiscal year ended December 29, 2012, as filed with the SEC, and subsequent SEC filings, including the company's Quarterly Reports on Forms 10-Q. Copies of the company's SEC filings are available at <http://investors.formfactor.com/edgar.cfm>. The company assumes no obligation to update the information in this press release, to revise any forward-looking statements or to update the reasons actual results could differ materially from those anticipated in forward-looking statements.

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